

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2774589

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALEX KALNITSKY	02/27/2014
KONG-BENG THEI	02/26/2014
CHIEN-CHIH CHOU	02/26/2014
CHEN-LIANG CHU	02/26/2014
HSIAO-CHIN TUAN	02/27/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED
Street Address:	NO. 8, LI-HSIN ROAD 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	30077
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14184900
CORRESPONDENCE DATA	
Fax Number:	(216)373-3450
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2166540090
Email:	docketing@cooperlegalgroup.com
Correspondent Name:	COOPER LEGAL GROUP LLC
Address Line 1:	6505 ROCKSIDE ROAD SUITE 330
Address Line 2:	SUITE 330
Address Line 4:	INDEPENDENCE, OHIO 44131
ATTORNEY DOCKET NUMBER:	TSMC2013-0165
NAME OF SUBMITTER:	DAVID J. STEIN
SIGNATURE:	/David J. Stein/
DATE SIGNED:	03/19/2014
Total Attachments: 3	

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REEL: 032471 FRAME: 0089

ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Alex Kalnitsky	Kong-Beng Thei	Chien-Chih Chou
San Francisco, CA	Pao-Shan Village, TW	New Taipei City, TW

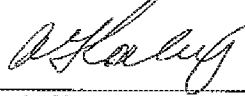
Chen-Liang Chu	Hsiao-Chin Tuan
Hsin-Chu City, TW	Ju Dong County, TW

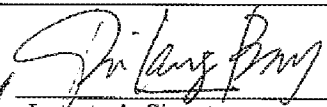
NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Alex Kalnitsky, Kong-Beng Thei, Chien-Chih Chou, Chen-Liang Chu and Hsiao-Chin Tuan, by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

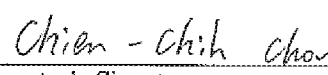
SEMICONDUCTOR ARRANGEMENT AND FORMATION THEREOF

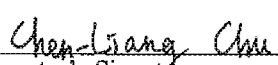
for which application for United States Letters Patent has been filed on _____ under Serial No. _____, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been

made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

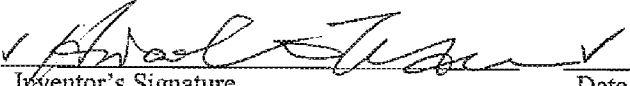
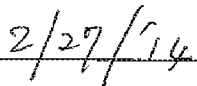
✓ <u></u> Inventor's Signature	✓ <u>2/27/2014</u> Date
<u>Alex Kalnitsky</u> Printed Name in English	

✓ <u></u> Inventor's Signature	✓ <u>2/26 '14</u> Date
<u>Kong-Beng Thei</u> Printed Name in English	

✓ <u></u> Inventor's Signature	✓ <u>2/26 '14</u> Date
<u>Chien-Chih Chou</u> Printed Name in English	

✓ <u></u> Inventor's Signature	✓ <u>2/26 '14</u> Date
<u>Chen-Liang Chu</u> Printed Name in English	

TSMC 2013-0165

	
Inventor's Signature	Date
Hsiao-Chin Tuan	
Printed Name in English	